

**Amendments to the Specification:**

Please replace paragraph [0030] with the following rewritten paragraph:

[0030] Fig. 9 is a magnified view of the area designated "C" in Fig. 8A;

Please replace paragraph [0056] with the following rewritten paragraph:

[0056] The housing 22 has an upper lip 22b and a lower lip 22c that each extend from a forward edge 22d thereof (see Figures [[1]] 2 and [[2]] 4). The upper lip 22b and the lower lip 22c each preferably have a slot 23 formed therein. The housing 22 can be equipped with an optional outer cover 25. The significance of these features is explained below.

Please replace paragraph [0059] with the following rewritten paragraph:

[0059] Each PCB 20 has a plurality of conductive signal traces 28 formed on a first side surface 20e thereof (see Figures 5, 6A, and 6B), and a ground plane 30 formed on a second side surface 20f thereof (see Figure 6C). The signal traces 28 each extend between a position proximate a lower edge 20c of the corresponding PCB 20, and a position proximate the forward edge 20d of the corresponding PCB 20. (A ground plane (not shown) can also be formed on the first side surface 20e, away from the signal traces 28.).

Please replace paragraph [0061] with the following rewritten paragraph:

[0061] The ground plane 30 is electrically coupled to ground pads [[42]] 38 located on the first and second side surfaces 20e, 20f of the PCB 20, proximate the lower edge 20c. Each ground pad [[42]] 38 located on the first side surface 20e is electrically coupled to a corresponding ground pad [[42]] 38 located on the second side surface 20f by way of a via.

Please replace paragraph [0070] with the following rewritten paragraph:

[0070] Each PCB 50 has a plurality of conductive signal traces 58 formed on a first side surface 50e thereof (see Figure 8B; the signal traces are not shown in Figure 8A, for clarity. Each PCB 50 also includes a ground plane 60 formed on a second side surface 50f thereof (see Figure 8C). The signal traces 58 each extend between a position proximate a

lower edge 50c of the corresponding PCB 50, and a position proximate a forward edge 50d of the corresponding PCB 50. (A ground plane (not shown) can also be formed on the first side surface 50e, away from the signal traces 58.).

Please replace paragraph [0072] with the following rewritten paragraph:

[0072] Each of the signal traces 58 is also electrically coupled to a corresponding set of second signal pads 63. One of the second signal pads 63 in each set is located on the first side surface 50e of the PCB 50, and the other of the second signal pads 63 in each set is located on the second side surface 50f. The second signals pads 63 in each set are electrically coupled by way of a via. The second signals pads 64 are each located ~~proximate~~ along the ~~forward~~ lower edge ~~[[50d]]~~ 50c of the PCB 50.

Please replace paragraph [0076] with the following rewritten paragraph:

[0076] The arm 66b and the angled portion 66c ~~[[are]]~~ engage a corresponding PCB 50 proximate the forward edge 50d thereof. More particularly, the arm 66b and the angled portion 66c of each signal contact 66 are spaced apart so that insertion of the forward edge 50d between the arm 66b and the angled portion 66c causes the arm 66b to resiliently flex away from the angled portion 66c. Continued insertion of the forward edge 50d into the space between the arm 66b and the angled portion 66c, in combination with the resilience of the arm 66b, causes the arm 66b and the angled portion 66c to securely engage the respective sides 50e, 50f of the PCB 50. In other words, the end portion 66a of each signal contact 66 acts substantially as a tuning-fork-type contact.

Please replace paragraph [0078] with the following rewritten paragraph:

[0078] Each signal contact 66 also comprises an elongated beam portion 66d unitarily formed with and extending from the angled portion 66c. Each signal contact 66 further comprises a substantially rounded contact portion 66e unitarily formed with the beam portion 66d, and positioned at an end of the beam portion 66d opposite the angled portion 66c. The optimal width ("z"-axis dimension) of the contact portion 66e is substantially independent of the optimal width ("z"-axis dimension) of the beam portion 66d. In particular, the width of the ~~contact portion 66e~~ beam portion 66d is selected based on the

desired spring rate of the contact portion 66e. The width of the contact portion 66e is selected based on the desired amount of float ~~of the~~ between the plug 12 ~~[[an]]~~ and the receptacle 14.

Please replace paragraph [0097] with the following rewritten paragraph:

[0097] The PCBs 20 of alternative embodiments may be configured so that the forward-most portion thereof is thinner than a remainder of the PCB 20, thereby providing the forward-most portion with greater flexibility and enhancing the ability of the forward-most portion to flex in response to misalignment between the plug 12 and the receptacle 14. The forward-most portion of each PCB 20 can also be contoured, e.g., wave-shaped, to achieve this effect (see the alternative embodiment of the PCB 20 designated ~~[[20i]]~~ 20j in Figure 13). Moreover, coplanar striplines can be substituted for the portions of the signal traces and ground planes 60 on the forward-most portion of each PCB 20 to reduce the potential for fatigue-induced failures in the signal and ground traces 58, 60 caused by repeated flexing. (It should be noted that the aspect ratio of the PCB ~~[[20i]]~~ 20j is not drawn to scale in Figure 13. In particular, the thickness ("y"-axis dimension) of the PCB ~~[[20i]]~~ 20j is exaggerated in relation to the length ("x"-axis dimension) in Figure 13.)